

Description

SK C2-08 is an effective stencil cleaner designed to clean SMT stencils at room temperature. The unique formulation rapidly removes solder paste, uncured inks and paste flux easily and cleanly. SK C2-08 can also be used for stencil underside wiping within the printer and manual wiping operations.

Specification

Colour	Clear
Form	Liquid
Odour	Light Hydrocarbon
Flash Point	>61°C
Specific Gravity @20 °C	0.8
Boiling point	>175°C

Application

SK C2-08 can be used for spray in air, spray pressure or ultrasonic as a mechanical separator. SK C2-08 leaves a micro film on the stencil which helps eliminate any moisture build up, ensuring repeatable, precise paste processing. The thin layer can be easily removed using a dry wipe or compressed air.

SK C2-08 is compatible with stainless steel, carbon steel, polyethylene, polypropylene and polyester.

SK C2-08 is not compatible with natural rubber, butyl rubber, EPDM and polystyrene.

Safety information

Always read safety data sheet before use. Wear nitrile gloves, safety glasses and ensure adequate ventilation or protection.

Storage

Storage - This product is not corrosive or ozone depleting. Though non flammable at ambient temperatures, do not store near open flame or ignition sources.

Shelf Life **Un-opened containers** -24 months in un-opened containers.

Benefits

Stencil cleaner for effective removal of solder paste, uncured inks and paste flux at room temperature.

Effective for stencil under wiping in printers

Can be used as spray in air, spray pressure or ultrasonic as a mechanical separator.

Flashpoint >61°C allowing it to be classified as non flammable.

Moderate evaporation rate

Environmentally friendly, with low odour and no ozone depleting substances.



Availability

Solderking manufacture all cleaners in the UK. SK C2-08 is available in the following plastic bottles.

Flux	Packaging
SK C2-08 Stencil Cleaner	0.5 Litre
	1 Litre
	5 Litre,
	10 Litre
	25 Litre
Stencil wipe buckets	100 wipes